

STY145N65M5

Datasheet — preliminary data

N-channel 650 V, 0.012 Ωtyp., 138 A, MDmesh[™] V Power MOSFET in Max247 package

Features

| Order code | V _{DSS} @T _{Jmax} | R _{DS(on)} max | I _D |
|-------------|--|-------------------------|----------------|
| STY145N65M5 | 710 V | < 0.015 Ω | 138 A |

- Max247 worldwide best R_{DS(on)}
- Higher V_{DSS} rating
- Higher dv/dt capability
- Excellent switching performance
- Easy to drive
- 100% avalanche tested

Applications

Switching applications

Description

The device is an N-channel MDmesh[™] V Power MOSFET based on an innovative proprietary vertical process technology, which is combined with STMicroelectronics' well-known PowerMESH[™] horizontal layout structure. The resulting product has extremely low onresistance, which is unmatched among siliconbased Power MOSFETs, making it especially suitable for applications which require superior power density and outstanding efficiency.

Table 1. Device summary

| Order code | Marking | Package | Packaging |
|-------------|----------|---------|-----------|
| STY145N65M5 | 145N65M5 | Max247 | Tube |

change without notice.

This is preliminary information on a new product now in development or undergoing evaluation. Details are subject to

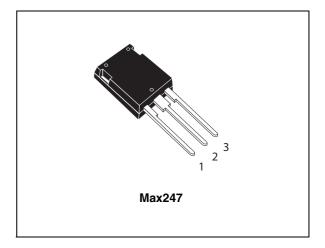
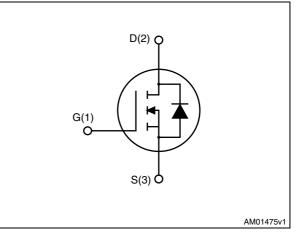


Figure 1. Internal schematic diagram



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Electrical ratings 1

| Table 2. | Absolute maximum ratings |
|----------|--------------------------|
| Table 2. | Absolute maximum ratings |

| Symbol | Parameter | Value | Unit |
|----------------------|---|-------------|------|
| -, | | | |
| V_{GS} | Gate- source voltage | ± 25 | V |
| I _D | Drain current (continuous) at $T_C = 25 \ ^{\circ}C$ | 138 | Α |
| ۱ _D | Drain current (continuous) at T _C = 100 °C | 87 | Α |
| $I_{DM}^{(1)}$ | Drain current (pulsed) | 552 | А |
| P _{TOT} | Total dissipation at $T_C = 25 \ ^{\circ}C$ | 625 | W |
| I _{AR} | Max current during repetitive or single pulse avalanche (pulse width limited by T_{JMAX}) | 17 | А |
| E _{AS} | Single pulse avalanche energy (starting $T_j = 25^{\circ}C$, $I_D = I_{AR}$, $V_{DD} = 50V$) | 2420 | mJ |
| dv/dt ⁽²⁾ | Peak diode recovery voltage slope | 15 | V/ns |
| T _{stg} | Storage temperature | - 55 to 150 | °C |
| Тj | Max. operating junction temperature | 150 | °C |

1. Pulse width limited by safe operating area.

2. I_{SD} \leq 138 A, di/dt = 400 A/µs, V_{DD} = 400 V, peak V_{DS} < V_{(BR)DSS}.

| Table 3. | l hermal data | | |
|-----------------------|--|-------|------|
| Symbol | Parameter | Value | Unit |
| R _{thj-case} | Thermal resistance junction-case max | 0.2 | °C/W |
| R _{thj-amb} | Thermal resistance junction-ambient max | 30 | °C/W |
| Τ _Ι | Maximum lead temperature for soldering purpose | 300 | °C |

Table 2 Thormal data



2 Electrical characteristics

(T_C = 25 °C unless otherwise specified)

| Symbol | Parameter | Test conditions | Min. | Тур. | Max. | Unit |
|----------------------|--|--|------|-------|-----------|----------|
| V _{(BR)DSS} | Drain-source breakdown voltage | $I_{D} = 1 \text{ mA}, V_{GS} = 0$ | 650 | | | V |
| I _{DSS} | Zero gate voltage drain current (V _{GS} = 0) | V _{DS} = 650 V V _{DS} = 650 V, T _C =125 °C | | | 10 100 | μΑ μΑ |
| I _{GSS} | Gate-body leakage current (V _{DS} = 0) | V _{GS} = ± 25 V | | | ±100 | nA |
| V _{GS(th)} | Gate threshold voltage | $V_{DS} = V_{GS}$, $I_D = 250 \ \mu A$ | 3 | 4 | 5 | V |
| R _{DS(on)} | Static drain-source on- resistance | V _{GS} = 10 V, I _D = 69 A | | 0.012 | 0.015 | Ω |

Table 4. On /off states

Table 5. Dynamic

| Symbol | Parameter | Test conditions | Min. | Тур. | Max. | Unit |
|--|--|--|------|--------------------|------|----------------|
| C _{iss} C _{oss} C _{rss} | Input capacitance Output capacitance Reverse transfer capacitance | V _{DS} = 100 V, f = 1 MHz, V _{GS} = 0 | - | 18500 413 11 | - | pF pF pF |
| C _{o(tr)} ⁽¹⁾ | Equivalent capacitance time related | $V_{GS} = 0, V_{DS} = 0$ to 520 V | - | 1950 | - | pF |
| C _{o(er)} ⁽²⁾ | Equivalent capacitance energy related | $V_{GS} = 0, V_{DS} = 0$ to 520 V | - | 415 | - | pF |
| R _G | Intrinsic gate resistance | f = 1 MHz open drain | - | 0.7 | - | Ω |
| Qg | Total gate charge | $V_{DD} = 520 \text{ V}, \text{ I}_{D} = 69 \text{ A},$ | | 414 | | nC |
| Q _{gs} | Gate-source charge | V _{GS} = 10 V | - | 114 | - | nC |
| Q _{gd} | Gate-drain charge | (see Figure 15) | | 164 | | nC |

1. $C_{o(tr)}$ is a constant capacitance value that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS} .

2. $C_{o(er)}$ is a constant capacitance value that gives the same stored energy as C_{oss} while V_{DS} is rising from 0 to 80% V_{DSS} .



| Symbol | Parameter | Test conditions | Min. | Тур. | Max. | Unit |
|---------------------|--------------------|---|------|------|------|------|
| t _{d(v)} | Voltage delay time | $V_{DD} = 400 \text{ V}, \text{ I}_{D} = 85 \text{ A},$ | | 255 | | ns |
| t _{r(v)} | Voltage rise time | R _G = 4.7 Ω, V _{GS} = 10 V | | 11 | | ns |
| t _{f(i)} | Current fall time | (see Figure 16) | - | 82 | - | ns |
| t _{c(off)} | Crossing time | (see <i>Figure 19</i>) | | 88 | | ns |

Table 6.Switching times

Table 7.Source drain diode

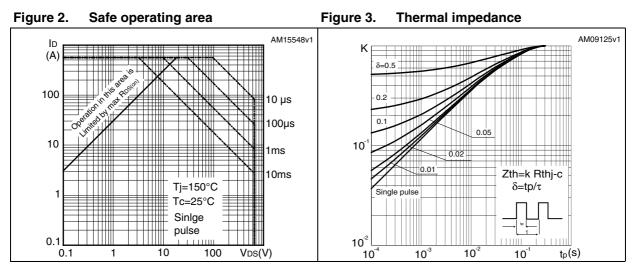
| Symbol | Parameter | Test conditions | Min. | Тур. | Max. | Unit |
|--|--|--|------|-------------------|------------|---------------|
| I _{SD} I _{SDM} ⁽¹⁾ | Source-drain current Source-drain current (pulsed) | | - | | 138 552 | A A |
| V _{SD} ⁽²⁾ | Forward on voltage | I _{SD} = 138 A, V _{GS} = 0 | - | | 1.5 | V |
| t _{rr} Q _{rr} I _{RRM} | Reverse recovery time Reverse recovery charge Reverse recovery current | I _{SD} = 138 A, di/dt = 100 A/μs V _{DD} = 100 V (see <i>Figure 16</i>) | - | 568 14.5 51 | | ns μC Α |
| t _{rr} Q _{rr} I _{RRM} | Reverse recovery time Reverse recovery charge Reverse recovery current | $\begin{split} I_{SD} &= 138 \text{ A, di/dt} = 100 \text{ A/}\mu\text{s} \\ V_{DD} &= 100 \text{ V, } \text{T}_{\text{j}} = 150 ^{\circ}\text{C} \\ (\text{see Figure 16}) \end{split}$ | - | 728 24.5 67 | | ns μC Α |

1. Pulse width limited by safe operating area.

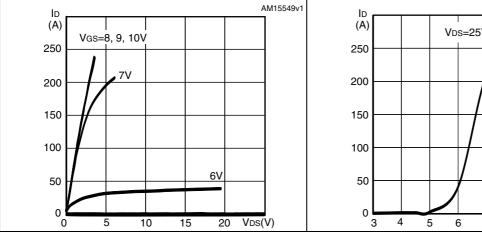
2. Pulsed: pulse duration = 300 μ s, duty cycle 1.5%



Electrical characteristics (curves) 2.1









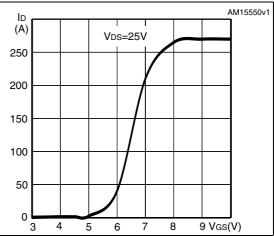
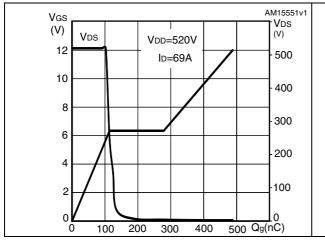
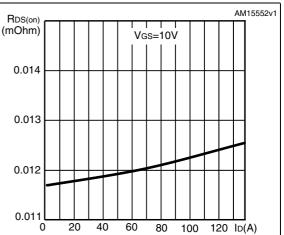


Figure 6. Gate charge vs gate-source voltage Figure 7. Static drain-source on-resistance





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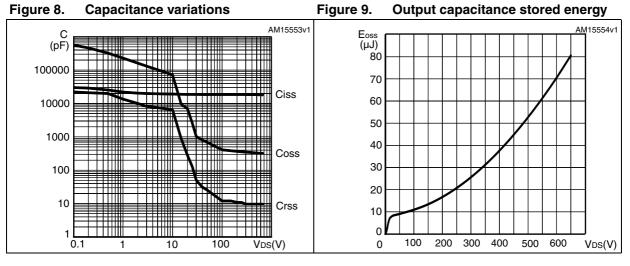
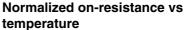


Figure 10. Normalized gate threshold voltage Figure 11. Normalized on-resistance vs vs temperature



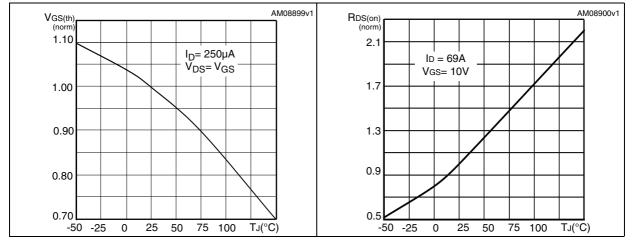
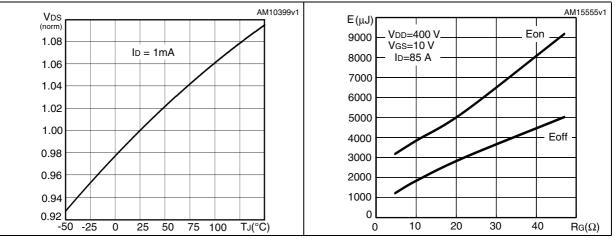


Figure 12. Normalized B_{VDSS} vs temperature

Switching losses vs gate Figure 13. resistance⁽¹⁾

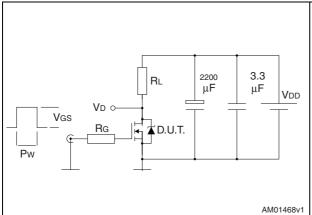


1. Eon including reverse recovery of a SiC diode.



3 Test circuits

Figure 14. Switching times test circuit for resistive load



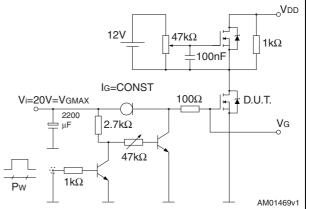
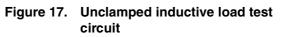


Figure 15. Gate charge test circuit

Figure 16. Test circuit for inductive load switching and diode recovery times



L

J

D.U.T.

2200

μF

-

3.3

μF

Vdd

AM01471v1

Vd o

lр

0

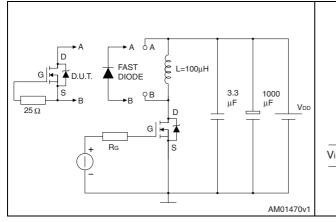
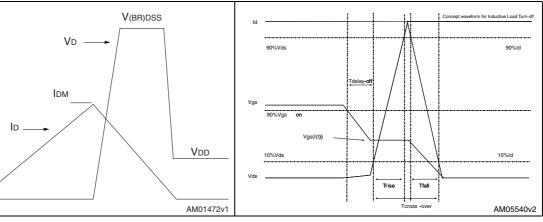




Figure 19. Switching time waveform



Pw



Vdd

4 Package mechanical data

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| Dim. | | mm | |
|-------|-----------|-------------|-------|
| Dini. | Min. | Тур. | Max. |
| А | 4.70 | | 5.30 |
| A1 | 2.20 | | 2.60 |
| b | 1.00 | | 1.40 |
| b1 | 2.00 2.40 | | 2.40 |
| b2 | 3.00 3.40 | | 3.40 |
| С | 0.40 | 0.40 0 | |
| D | 19.70 | 19.70 2 | |
| е | 5.35 5.55 | | 5.55 |
| E | 15.30 | 15.30 15.90 | |
| L | 14.20 | | 15.20 |
| L1 | 3.70 | | 4.30 |

 Table 8.
 Max247 mechanical data



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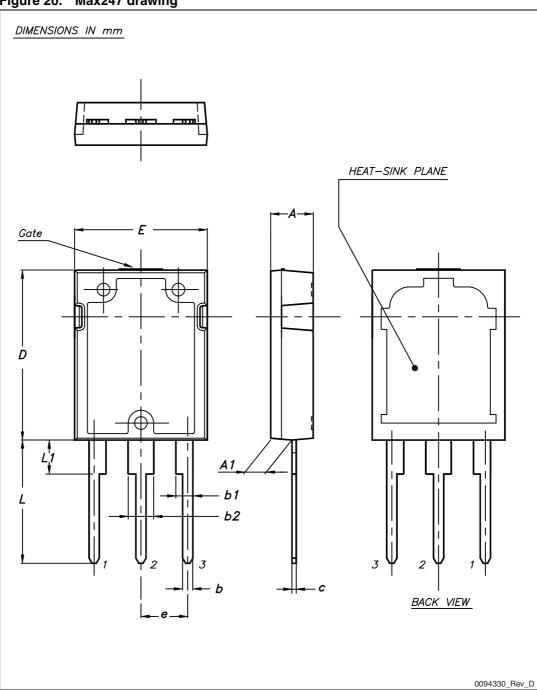
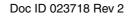


Figure 20. Max247 drawing



5 Revision history

Table 9.Document revision history

| Date | Revision | Changes |
|-------------|----------|---|
| 25-Sep-2012 | 1 | First release. |
| 17-Jan-2013 | 2 | Modified: I_{AR} and E_{AS} values Modified: typical values on <i>Table 5</i>, <i>6</i> and <i>7</i> |



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